IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:

Wayne G. RENKEN

Title:

Process Condition Sensing Wafer and Data Analysis System

.

October 14, 2003

Application No.:

10/685,550

Filing Date:

Group Art Unit:

2856

Examiner: Docket No.: Hezron WILLIAMS SENS.005US1

Conf. No.:

4924

Mail Stop RCE Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

AMENDMENT ACCOMPANYING RCE

Sir

This is in response to the final Office Action dated March 16, 2006, setting a period for response expiring on June 16, 2006. An appropriate request for extension of time accompanies this paper.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims begin on page 3 of this paper.

Amendments to the Drawings are not being made.

Remarks begin on page 8 of this paper.